

Bill of Materials

TI DESIGNS

TIDA-WL1835MODCOM8B

Item	Qty	Reference	Value	Part Description	Manufacturer	Package Reference	Manufacturer Part Number
1	1	U1		TI WL1835 WiFi/BT Module	TI	13.4 x 13.3 x 2.0mm	(X) WL1835MODGB
2	1	OSC1		XOSC 3225 / 32.768KHZ / 1.8V / ±50ppm	TXC	3.2 x 2.5 x 1.0mm	7XZ3200005
3	2	ANT1, ANT2		ANT / Chip / 2.4GHZ, 5GHZ / Peak Gain >5dBi	TDK	1.6 x 0.8mm	ANT016008LCD2442MA
4	3	J1, J3, J4		CON Male 1x2 / Pitch	承清	H-1x2-2.0mm	P301-SGP-040/028-02
5	2	J1, J3		DC JUMPER / PITCH 2.0mm	承清	-	CMJ-20BB
6	2	J5, J6		Mini RF Header Receptacle	Hirose	3.0 x 2.5 x 1.25mm	U.FL-R-SMT-1(10)
7	1	L1	1.1nH	IND 0402 / 1.1nH / ±0.05nH / SMD	Murata	0402	LQP15MN1N1W02
8	1	L2	1.5nH	IND 0402 / 1.5nH / ±0.05nH / SMD	Murata	0402	LQP15MN1N5W02
9	1	C11	1.2pF	CAP 0402 / 1.2pF / 50V / COG / ±0.1pF	Murata	0402	GJM1555C1H1R2BB01
10	1	C9	2.2pF	CAP 0402 / 2.2pF / 50V / COG / ±0.1pF	Murata	0402	GJM1555C1H2R2BB01
11	1	C14	4pF	CAP 0402 / 4pF / 50V / COG / ±0.1pF	Murata	0402	GJM1555C1H4R0BB01
12	1	C13	8pF	CAP 0402 / 8pF / 50V / COG / ±0.1pF	Murata	0402	GJM1555C1H8R0BB01
13	2	C7, C8	10pF	CAP 0402 / 10pF / 50V / NPO / ±5%	Murata	0402	0402N100J500LT
14	2	C3, C4	0.1uF	CAP 0402 / 0.1uF / 10V / X7R / ±10%	Murata	0402	0402B104K100CT
15	1	C1	1uF	CAP 0402 / 1uF / 6.3V / X5R / ±10% / HF	Murata	0402	GRM155R60J105KE19D
16	1	C2	10uF	CAP 0603 / 10uF / 6.3V / X5R / ±20%	Murata	0603	C1608X5R0J106M
16-2	-	-	10uF	CAP 0603 / 10uF / 6.3V / X5R / ±20%	Walsin	0603	0603X106M6R3CT
17	30	R1, R2, R3, R4, R6, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, R17, R18, R19, R21, R22, R23, R24, R25, R26, R27, R28, R29, R30, R31, R32	OR	RES 0402 / OR / ±5%	Walsin	0402	WR04X000 PTL
18	1	R20	10K	RES 0402 / 10K / ±5%	Walsin	0402	WR04X103 JTL
19	1	-		PCB WL1835MODCOM8B D01 / Layer 4 / FR4 (4pcs/PNL)	承清	76.0 x 31.0 x 1.0mm	-

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